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# Molding Compounds for General Packages

## High Reliable and Easy-to-Use Molding Compounds for Various Type of Packages

### Strong Points

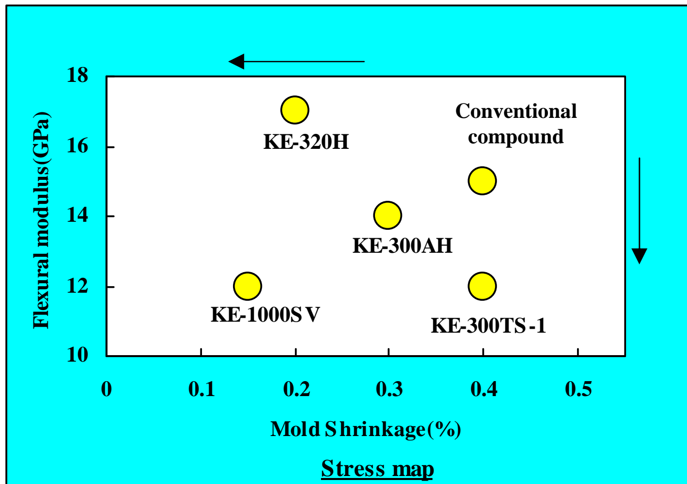
a) Provide Various Molding Compounds with High Reliability to Cover Many Applications such as LSI, Transistors and Diodes.
b) Good Curability and Applicable to Various Molding Machines (Both Automated and Conventional)
c) Low Stress of Large chips and Applicable to Encapsulation.

### Application

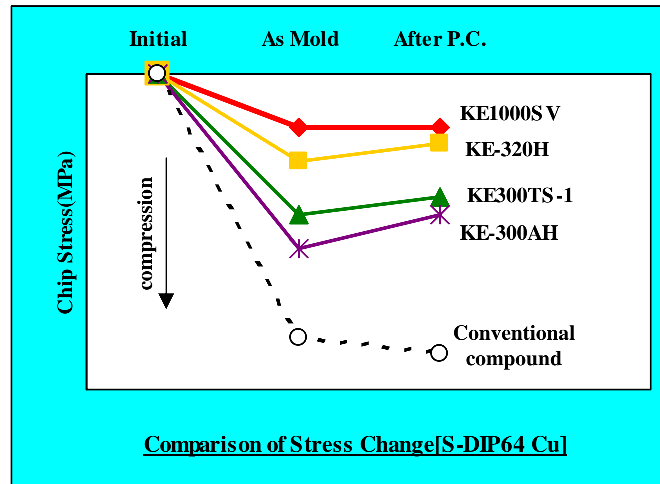
・Smaller SOP ・Smaller QFP ・DIP ・SIP/ZIP ・TO-PKG
・DPAK ・SOT・Unbalanced PKG ・Module

### General Properties

| Item | | Units | KE-300TS-1 | KE-300AH | KE-320H | KE-1000SV | KE-G200V | KE-G240V |
|---|---|---|---|---|---|---|---|---|
| Spiral flow | | cm | 90 | 90 | 65 | 95 | 95 | 85 |
| Gel time | | s | 30 | 22 | 23 | 28 | 27 | 21 |
| Specific gravity | | - | 1.8 | 1.9 | 1.9 | 1.8 | 2.0 | 2.0 |
| C.T.E | α1 | $x10^{-5}/^{o}C$ | 1.8 | 1.5 | 1.2 | 1.5 | 1.0 | 1.0 |
| | α2 | | 6.5 | 5.5 | 4.8 | 5.8 | 4.2 | 4.0 |
| Glass transfer temp. | | $^{o}C$ | 165 | 155 | 155 | 200 | 150 | 140 |
| Flexural strength | | MPa | 140 | 150 | 165 | 135 | 160 | 160 |
| Flexural modulus | | GPa | 12.5 | 13.5 | 17.0 | 12.5 | 22.0 | 22.0 |



Stress map



Comparison of Stress Change[S-DIP64 Cu]

Molding compounds

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